

Abstract Submitted
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Thermoelectric power factor of topological insulator $\text{Bi}_{2-x}\text{Sb}_x\text{Te}_{3-y}\text{Se}_y$ TE CHIH HSIUNG, TING YUAN CHEN, LI ZHAO, YI HSIN LIN, YANG YUAN CHEN, Institute of Physics, Academia Sinica, Taipei, Taiwan — Topological insulator (TI) is a new quantum material. The surface states of TIs are protected by time-reversal symmetry which allows charge carrier to propagate on the edge of surface conducting channel without scattering. $\text{Bi}_{1.5}\text{Sb}_{0.5}\text{Te}_{1.7}\text{Se}_{1.3}$ is a well-known TI [1] and thermoelectric material because of its promising thermoelectric performances at room temperature. The conversion efficiency of thermoelectric material is characterized by the dimensionless figure of merit ZT . Decades of effort were devoted to ZT optimization either through composition alteration or nanostructure fabrication. In this study, the temperature dependence of resistance of bulk (exfoliated specimen with $140\ \mu\text{m}$ thickness) shows semiconductor behavior ($0.04\ \Omega\ \text{cm}$ at $300\ \text{K}$) without saturating regime in lower temperatures. In contrast, its nanoflake counterpart ($100\text{-}500\ \text{nm}$) [2] shows a transition from semiconductor to metallic behavior near $100\text{--}150\ \text{K}$ with decreasing temperature and saturation at $10\ \text{K}$. Surface contribution to the total conductance of exfoliated specimens was acquired through Hall effect measurements in the magnetic field ranging from -9 to 9 Tesla. Surface contribution of BSTS samples increases from 3% to 70% as thickness decreases from 140 to $7\ \mu\text{m}$. In this work, we report a systematic study of thermoelectric power factor for various thicknesses of BSTS specimens to examine the thermoelectric power factor of their surfaces.

[1] Zhi Ren et al., Phys. Rev. B 84, 165311 (2011).

[2] Bin Xia et al., e-print arXiv1203.2997

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